External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.18	100.0	3.9
			Subtotal	0.18	100	3.9
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01	100.0	0.27
	Pure metal	Aluminium (Al)	7429-90-5	0.11	100.0	2.4
			Subtotal	0.12	200	2.67
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.34	90.0	7.2
	Lead alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0	0.5	0.04
	Lead alloy	Silver (Ag)	7440-22-4	0.01	2.5	0.2
	Lead alloy	Antimony (Sb)	7440-36-0	0.03	7.0	0.56
			Subtotal	0.38	100	8
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.12
	Copper alloy	Iron (Fe)	7439-89-6	0.02	0.1	0.4
	Copper alloy	Copper (Cu)	7440-50-8	18.7	99.87	399.48
			Subtotal	18.73	100	400
Heat Spreader	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.36
	Copper alloy	Iron (Fe)	7439-89-6	0.06	0.1	1.2
	Copper alloy	Copper (Cu)	7440-50-8	56.09	99.87	1198.44
			Subtotal	56.17	100	1200
Isolator	Copper alloy	Phosphorous (P)	7723-14-0	0	0.1	0.09
	Copper alloy	Aluminium Trioxide (Al2O3)	1344-28-1	3.86	91.6	82.44
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.04	0.9	0.81
	Copper alloy	Molybdenum (Mo)	7439-98-7	0.29	7.0	6.3
	Copper alloy	Manganese (Mn)	7439-96-5	0.02	0.4	0.36
			Subtotal	4.21	100	90
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.06	5.0	1.25
	Lead alloy	Silver (Ag)	7440-22-4	0.03	2.5	0.62
	Lead alloy	Lead (Pb)	7439-92-1	1.08	92.5	23.12
			Subtotal	1.17	100	24.99
Mould Compound		Bisphenol-A Bisphenol-A Diglycidyl Ether copolymer	25036-25-3	0.23	1.3	4.94
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.24	7.0	26.6
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	2.49	14.0	53.2
	Filler	Silica fused	60676-86-0	1.07	6.0	22.8
	Carbon Black	Carbon black	1333-86-4	0.07	0.4	1.52
	Filler	Misc. Silica compounds (generic)	14808-60-7	12.45	70.0	266
		Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.23	1.3	4.94
			Subtotal	17.78	100	380
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.26	100.0	27
			Subtotal	1.26	100	27
			Total	100	100	2136.56

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